

3. (Previously presented) The method as recited in claim 1, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.
4. (Previously presented) The method as recited in claim 1, wherein the conductive material is a conductive adhesive.
5. (Previously presented) The method as recited in claim 1, wherein one or more of the conductive layers is grounded to the controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.
6. (Cancelled)
7. (Cancelled)
8. (Cancelled)
9. (Previously presented) The method as recited in claim 1, wherein the conductive material is plated solder.
10. (Previously presented) The method as recited in claim 1, wherein the conductive material is screen solder.
11. (Previously presented) The method as recited in claim 1, wherein the conductive material is solder, and further comprising reflowing the solder.
12. (Cancelled)

13. (Cancelled)
14. (Previously presented) The method as recited in claim 1, further comprising forming the cross shaped via by etching exposing the exposed portions of the at least one conductive layer.
15. (Previously presented) The method as recited in claim 1, wherein the conductive layers form part of a lead suspension for suspending an electronic component.
16. (Previously presented) The method as recited in claim 15, wherein the electronic component is a magnetic head.
17. (Withdrawn) A method as recited in claim 14, wherein the finger is welded in place.
18. (Withdrawn) A method as recited in claim 1, wherein the conductive material is a finger formed by etching, the finger being sandwiched between a mount plate and a load beam.
19. (Withdrawn) A method as recited in claim 18, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel
20. (Withdrawn) A method as recited in claim 18, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.
21. (Withdrawn) A method as recited in claim 18, wherein the finger is welded in place.

22. (Withdrawn) A method as recited in claim 1, further comprising an extraneous conductive layer, the conductive material being a dimple extending from the extraneous conductive layer and contacting the exposed portions of the conductive layers.

23. (Withdrawn) A method as recited in claim 22, wherein the dimple extends through a via in at least one of the conductive layers.

24. (Withdrawn) A method as recited in claim 22, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layer is stainless steel.

25. (Withdrawn) A method as recited in claim 22, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.

26. (Withdrawn) A method as recited in claim 1, wherein the portions of the conductive layers are exposed by punching a hole through the conductive layers, the conductive material extending through the hole.

27. (Withdrawn) A method as recited in claim 26, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

28. (Withdrawn) A method as recited in claim 26, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.